# **TEMIC / MATRA MHS RADIATION TOLERANT SPARC PROCESSOR**

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# AGENDA

- TEMIC
- MATRA space strategy and product offering
- Radiation tolerant SPARC program
- SPARC statusSPARC performances
- SPARC offering
- SPARC development support
- Forecast/conclusion







# **Revenue Structure by Market Segments**



# **TEMIC DUAL USE**

- RT processes are only slight deviations from standards
- Non RT & RT products are mask compatible
- Non RT & RT products take advantage of volume based production:
  - ▼available in any packages to any quality grades
  - ▼better manufacturing & quality control
  - ▼broader innovation capability
  - **▼**lower manufacturing cost
  - ▼better reproducibility
  - **▼**better longevity



#### **TEMIC DUAL USE**



- TEMIC has been a pioneer, from company day one
- The only long term reliable route to keep servicing space
- The only route for space advanced technology availability
- The TEMIC brochure supports and emphasizes that strategy
- William PERRY supports it
- And everybody wants now to go that way !



RAD-PACK is a SEI trademark

**TEMIC** 

#### Services offering

Aerospace & Defense



## **Historical Context**

- ESA intended to launch a new Microprocessor development programme
- Need of a space 32 bits Microprocessor from a European supplier
- Only MIL31750 was available on SOS technology, and wasn't powerful enough
- MHS was a good candidate with the SPARC architecture, and also thanks to its advanc radiation tolerant technology .
- Then, the SES, Matra Marconi Space and MHS consortium was selected to design a 32 t Computer named ERC 32 .

## **32 BIT SPARC PRODUCT LINES**



# **MHS SPARC program**



#### **TSC690E status**

- Respective chips revision C, B and A are validated on DMS-R (beta site)
  Available :
  - ▼691E(IU), 692E(FP) and 693E(MEC) VHDL models ▼respective chips revision are C, B and A
- Specifications : ▼rev G, dated 10/09/96 for 691E and 692E ▼rev B, dated 23/04/96 for 693E.
- Order entry open for C, B and A chips
- Irradiation completed :
  - Vtotal dose at DCAN (France)
     SEU and latchup at Brookhaven Labs (USA)



#### **TSC690E** features

- Full functional compatibility with former 90C601 (IU) & 90C602 (FP)
- 100% compatible with SPARC V7
- Concurrent Error Detection
- Testability :
  - ▼Off-line testing with, at least, 95% fault coverage
- System self test after Power-On Reset covering 90% of the core
- Performance :
  - ▼10 Mips / 2 Mflops (SP) @ 14 MHz
- Power consumption : ▼lower than 5 W (ERC32) @ 10 Mips
- Operating conditions : ▼temperature range : -55°C to +125°C
  - ▼voltage range : 4.5V to 5.5V



#### **TSC690E** radiation features

- Total dose radiation (Gamma) :
   ▼base line better than 50 Krads (Si)
   ▼dual use process approach allowing non RT & RT versions
- SEU LET Threshold better than 15 MeV / cm2
- Latch up free (better than 100MeV)
- and over 97% of all SEU induced faults are detected and trapped



## Fault tolerant & test mechanisms

- Parity checking for all latches with generation of hardware error traps
- Parity checking for address, data & control busses
- Possibility to disable bus parity checking (internal still working)
- Master / checker operation for 691E and 692E
- Interleaving of register file bits for better SEU detection
- IEEE standard test access port
- Internal scan path
- Halt mode
- Program flow control (691E only)
- Operating & stand by power consumption reduction
- Process & design improvements for SEU & total dose
- Manufactured on space hardened 0.8 µm CMOS process



# **TSC691E** features

- Full software compatibility with 90C601
- 8 windows register files
- FPU interface allows concurrent execution of FP instructions
- User / supervisor modes for multitasking
- Fault tolerant & test mechanisms improvements
- Packaged into an MQFPF256(as TSC693E)



TSC691E diagram

## **TSC692E** features

- Compatibility with 90C602 instructions set
- Full compliance with ANSI/ IEEE 754 for binary FP arithmetic
- 90C602E never generates unfinished FP operation exception
- Supports single and double precision FP operations
- Tightly coupled IU interface
- 64 bit ALU and multiplier/divide/square root
- 16 64-bit or 32 32-bit registers in 3 port FP register file
- Fault tolerant & test mechanism improvements
- Packaged into an MQFPL160



#### **TSC692E diagram**

## **TSC693E** features

- Address decoding & memory interface
- Wait state generation
- Interrupt controller
- 32-bit SEC/DED
- Two 32-bit timers
- Two UARTs
- Boot PROM interface
- DMA interface
- Error manager
- Watchdog
- Packaged into MQFPF256 (as TSC691E)



# TSC693E diagram



# Exemple of chips association



Master/Checker Operation



## **Targetted applications**

- TSC691E/TSC692E/TSC693E applications :
  - ▼ HARD REAL TIME
    - Attitude Orbit Control Satellite (AOCS), Control Navigation Guidance for Launcher, Spacecraft, Satellite platforms
  - ▼ DATA PROCESSING
    - Mission computer, Data management/storage for larger satellite and shorter ground communications
    - Dedicated payload processing
    - Worstations for Space stations
  - ▼ DATA HANDLING
    - Communication management
    - Data compression ( image : earth observation, datacommunication).
  - ▼ SMALL SATELLITE MULTIPLE COMPUTER USAGE
  - ▼ EMBEDDED APPLICATION

# Strengths

- Strong ESA recommandation for future developments
- · Baseline for a majority of the new European Computer developments
- SPARC software available and standard ADA language can be used
- Many hardwares available for prototype development
- Capability to evoluate towards Sparclet core for the new generation
- Well known RISC instructions set
- Well adapted for multi application development
- TEMIC silicon for good traceability



## **ERC32** quality flows

- So far, only delivered as packaged die, as follows :
  - ▼ a -E flow, which stands for engineering, which TEMIC will have available from the shelves, most of the time,
  - ▼ a -2 flow, which are parts packaged according MHS mil flow, with a mil temp range operating garantee, build on orders,
  - ▼ a P883 flow, which stands for MIL-STD-883 level B plus PIND test (TM2020 condition A), build on orders,
  - $\checkmark$  a SB flow, which stands for SCC9000 level B, build on orders.



PRODUCTS	COMPANY	AVAILABILITY	PRICE
ALSYS ADA	TSP / Alsys UK	Beta now	
VxWORKS C/C++	Wind River France	Available	
GNU C/C++	Public domain	Available	Free
RTEMS C/C++ RT kernel	OAR US	Available	Free
Rational ADA	Rational France	Available	

# ERC32 software development tools : simulators, debugger, analysis

PRODUCTS	COMPANY	AVAILABILITY	PRICE	
ERC32SIM (ERC32 sim ulator)	SPACEBEL Available Belgium		?	
SIS (ERC32 simulator)	ESTEC	Available	Free	
GDB & DDD (debugger and graphic user interface)	Public domain	Available	Free	
Execution analysis tools	SPACEBEL Belgium	?	?	

# ERC32 software development tools : hardwares

PRODUCTS	COMPANY	AVAILABILITY
VME Common Processor Board	MMS France	Available + specification
DEM32 ERC32 evaluation board	SES	Available + specification
AVECS VME board	DASA	?
SPARC RT VME single board computer	THARSYS France	?